



Material Content Data Sheet



Sales Product Name	TLE8110EE			Issued	20. July 2018			
MA#	MA001646828							
Package	PG-DSO-36-51			Weight*	610.68 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.562	2.55	2.55	25483	25483
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		372	
	non noble metal	iron	7439-89-6	4.546	0.74		7443	
wire	non noble metal	copper	7440-50-8	184.568	30.22	31.01	302236	310144
	non noble metal	copper	7440-50-8	2.355	0.39	0.39	3856	3856
	encapsulation	organic material	carbon black	1333-86-4	0.786	0.13		1287
encapsulation	plastics	epoxy resin	-	36.160	5.92		59214	
	inorganic material	silicondioxide	60676-86-0	356.099	58.31	64.36	583125	643626
leadfinish	non noble metal	tin	7440-31-5	5.440	0.89	0.89	8909	8909
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1295	1295
glue	plastics	epoxy resin	-	1.021	0.17		1672	
	noble metal	silver	7440-22-4	3.062	0.50	0.67	5015	6687
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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